

M59C

Silicon Controlled Switch

Driver for Numerical Indicator Tube Switching

■ Features

- Selective breakover voltage
- Low On-voltage

■ Absolute Maximum Ratings (Ta=25°C)

Item	Symbol	Value		Unit
		PNP	NPN	
Collector-Base Voltage	V_{CBO}	-70	70	V
Collector-Emitter Voltage	V_{CER}^{*1}		70	V
Collector-Emitter Voltage	V_{CEO}	-70		V
Emitter-Base Voltage	V_{EBO}	-70	5	V
Emitter Current	I_E	100	-100	mA
Peak Emitter Current	I_{EM}^{*2}	500	-500	mA
Collector Current	I_C		50	mA
Peak Collector Current	I_{CM}		100	mA
Power Dissipation	P_D	200		mW
Junction Temperature	T_J	150		°C
Storage Temperature	T_{stg}	-55 ~ +150		°C

*1 $R_{BE} = 10 \text{ k}\Omega$ *2 $t_w < 1 \text{ ms}$, $\delta = 0.05$

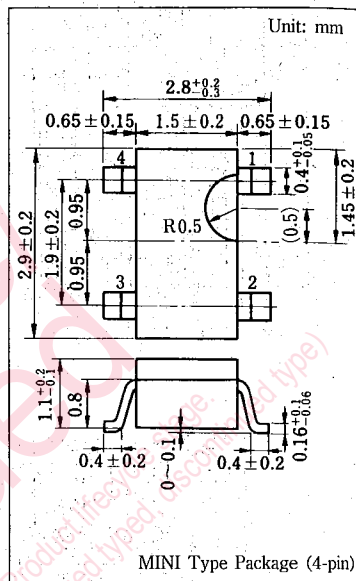
■ Electrical Characteristics (Ta=25°C)

Item	Symbol	Condition	min.	typ.	max.	Unit
(NPN transistor)						
Collector Cutoff Current	I_{CER}	$V_{CE} = 70 \text{ V}$, $R_{BE} = 10 \text{ k}\Omega$		10	100	nA
Emitter Cutoff Current	I_{EBO}	$V_{EB} = 5 \text{ V}$, $I_C = 0$		30	1000	nA
DC Current Gain	h_{FE}	$V_{CE} = 2 \text{ V}$, $I_C = 10 \text{ mA}$	50	180		
(PNP Transistor)						
Emitter Cutoff Current	I_{EBO}	$V_{EB} = -70 \text{ V}$, $I_C = 0$		-0.05	-100	nA
DC Current Gain	h_{FE}^*	$V_{CB} = 0$, $I_E = 1 \text{ mA}$	0.19	1.1	2.5	
(Coupling Characteristics)						
Forward Voltage	V_{AE}	$I_A = 50 \text{ mA}$, $I_C = 0$, $R_{BE} = 10 \text{ k}\Omega$		1.05	1.4	V
Holding Current (DC)	I_H	$R_{BE} = 10 \text{ k}\Omega$, $I_C = 10 \text{ mA}$, $V_{BB} = -2 \text{ V}$	0.1	0.5	1	mA
Turn-off Time	t_{off}	$R_{BE} = 10 \text{ k}\Omega$ *2		11	20	μs

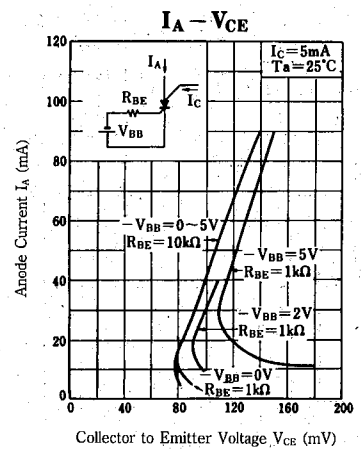
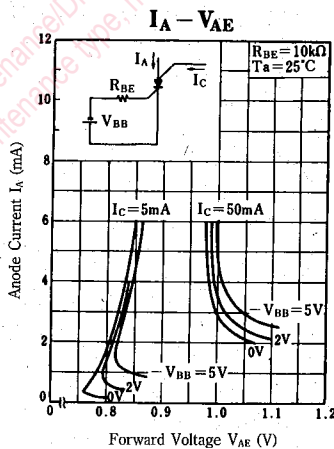
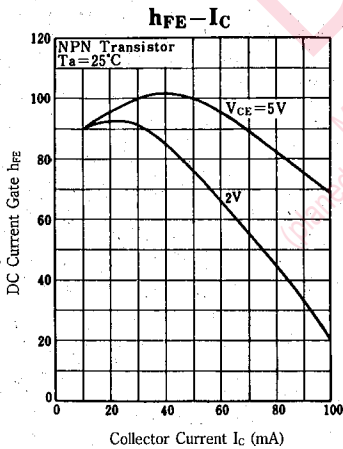
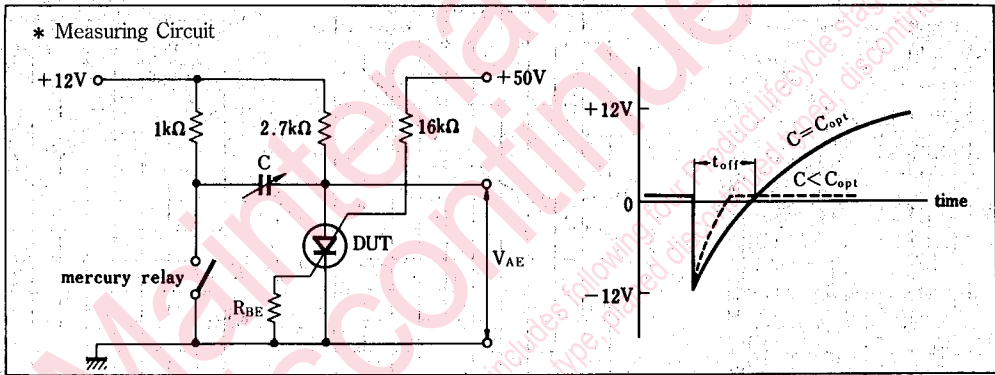
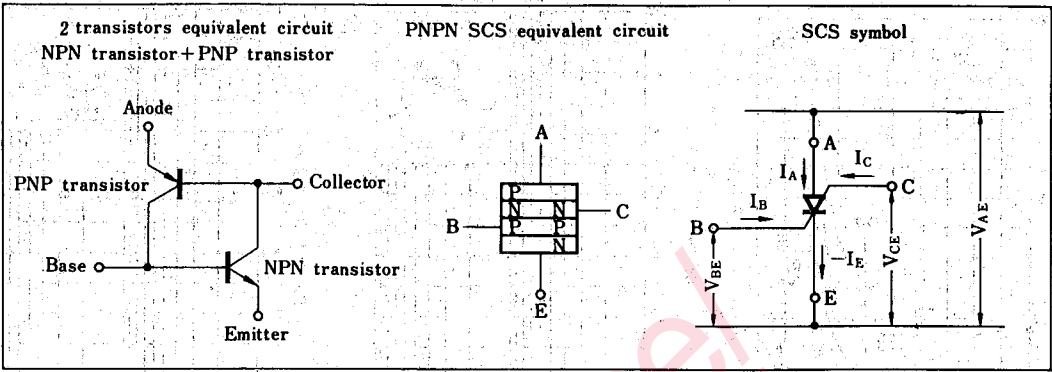
*2 t_r measuring circuit

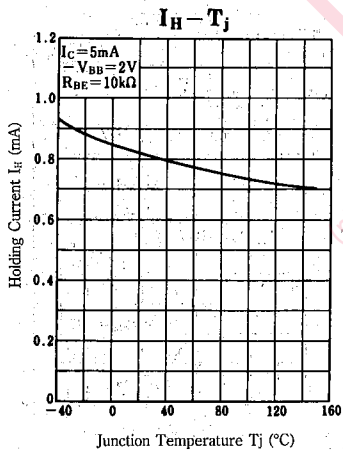
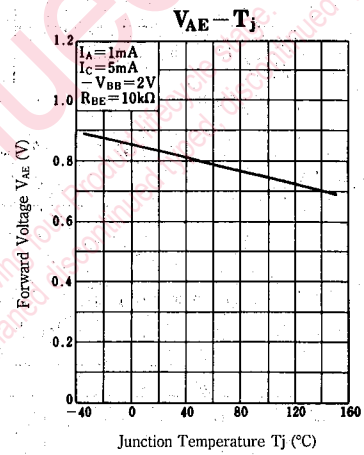
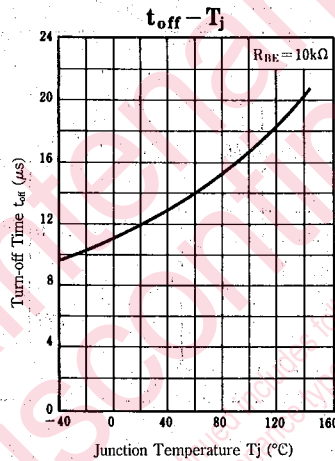
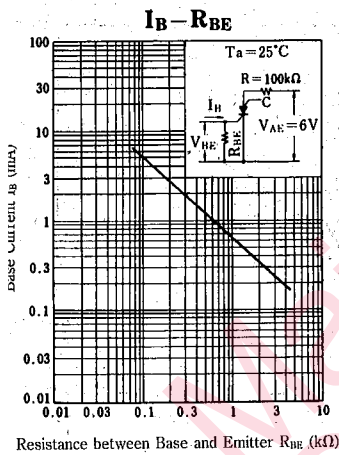
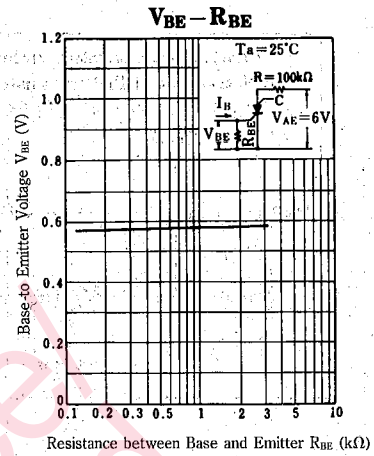
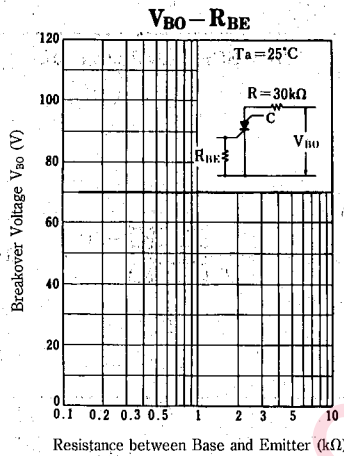
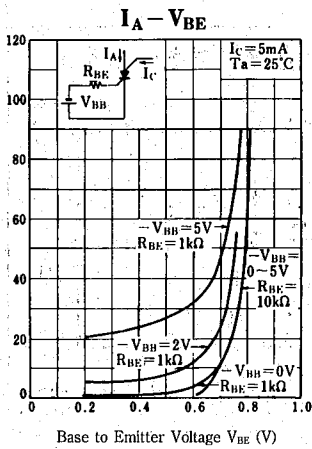
Class	P	Q
h_{FE} (PNP)	0.19~1.2	0.72~2.5

■ Package Dimensions



pin	①NPN Part	②PNP Part	③ Integrated Element
1	Collector	Base	AG
2	—	Emitter	A
3	Emitter	—	K
4	Base	Collector	AG





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